

### General Description

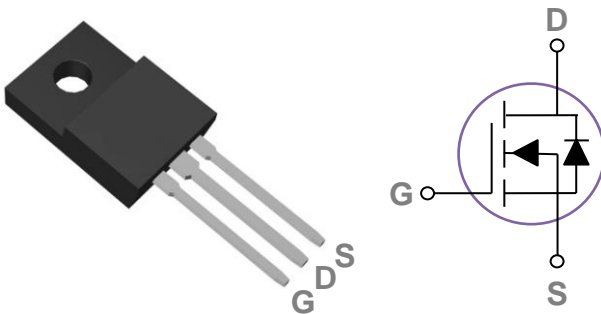
These N-Channel enhancement mode power field effect transistors are using super junction MOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDSON	ID
700V	600mΩ	8A

### Features

- 700V,8A,  $R_{DS(ON)} = 600m\Omega @ V_{GS} = 10V$
- Improved  $dv/dt$  capability
- Fast switching

### TO220F Pin Configuration



### Applications

- PFC Power Supply Stages
- Motor Control
- DC-DC Converters
- Adapter

### Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	700	V
$V_{GS}$	Gate-Source Voltage	$\pm 30$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ C$ )	8	A
	Drain Current – Continuous ( $T_c=100^\circ C$ )	5	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	32	A
EAS	Single Pulse Avalanche Energy	700	mJ
$P_D$	Power Dissipation ( $T_c=25^\circ C$ )	26	W
	Power Dissipation – Derate above $25^\circ C$	0.21	W/ $^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	4.8	$^\circ C/W$

**Electrical Characteristics ( $T_J=25\text{ }^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	700	---	---	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=700V, V_{GS}=0V, T_J=25^\circ C$	---	---	1	$\mu A$
		$V_{DS}=560V, V_{GS}=0V, T_J=100^\circ C$	---	---	10	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 30V, V_{DS}=0V$	---	---	$\pm 100$	nA

**On Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=2A$	---	520	600	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	2	3	4	V

**Dynamic and switching Characteristics<sup>2</sup>**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$Q_g$	Total Gate Charge	$V_{DS}=350V, V_{GS}=10V, I_D=4A$	---	16	24	nC
$Q_{gs}$	Gate-Source Charge		---	2	5	
$Q_{gd}$	Gate-Drain Charge		---	7	10.5	
$T_{d(on)}$	Turn-On Delay Time	$V_{DS}=350V, V_{GS}=10V, R_G=25\Omega, I_D=4A$	---	15	25	ns
$T_r$	Rise Time		---	30	45	
$T_{d(off)}$	Turn-Off Delay Time		---	90	135	
$T_f$	Fall Time		---	25	40	
$C_{iss}$	Input Capacitance	$V_{DS}=100V, V_{GS}=0V, F=1MHz$	---	535	800	pF
$C_{oss}$	Output Capacitance		---	20	30	
$C_{rss}$	Reverse Transfer Capacitance		---	1	3	
$R_g$	Gate resistance	$V_{GS}=0V, V_{DS}=0V, F=1MHz$	---	18	---	$\Omega$

**Guaranteed Avalanche Energy**

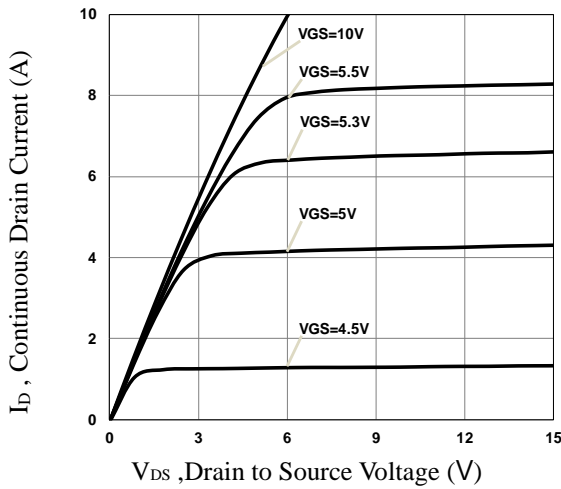
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
EAS	Single Pulse Avalanche Energy	$V_{DD}=100V, L=79.9mH, I_{AS}=2.5A$	250	---	---	mJ

**Drain-Source Diode Characteristics and Maximum Ratings**

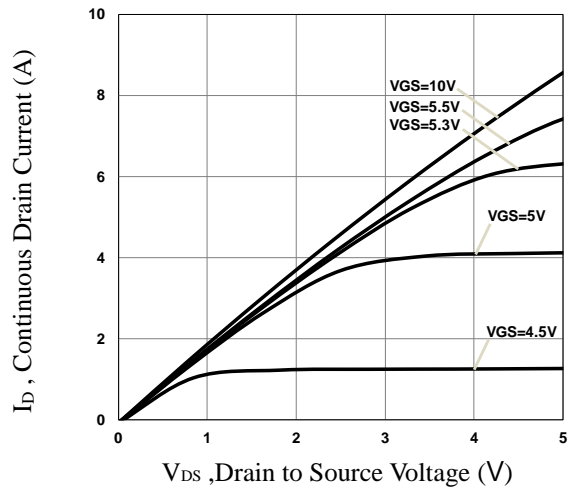
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V, \text{Force Current}$	---	---	8	A
$I_{SM}$	Pulsed Source Current		---	---	16	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V, I_S=4A, T_J=25^\circ C$	---	---	1.4	V
$t_{rr}$	Reverse Recovery Time	$V_R=400V, I_S=5A$	---	170	---	ns
$Q_{rr}$	Reverse Recovery Charge	$di/dt=100A/\mu s, T_J=25^\circ C$	---	2.9	---	$\mu C$

Note :

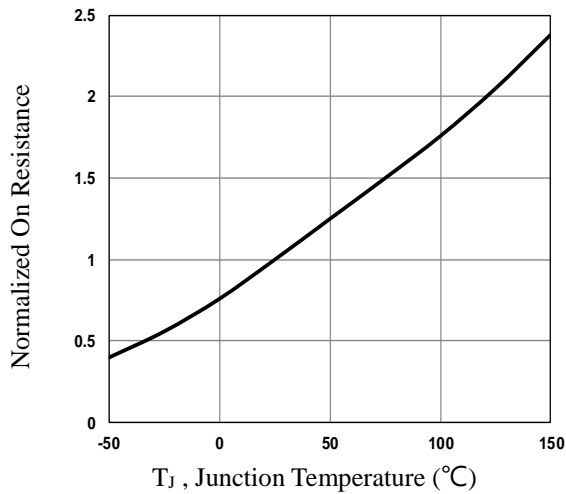
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. Essentially independent of operating temperature.



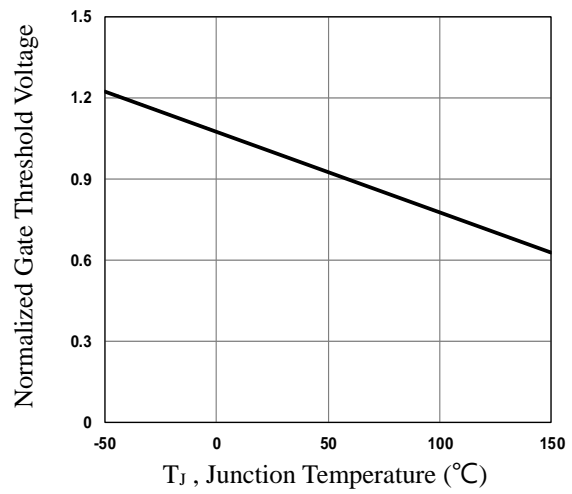
**Fig.1 Typical Output Characteristics**



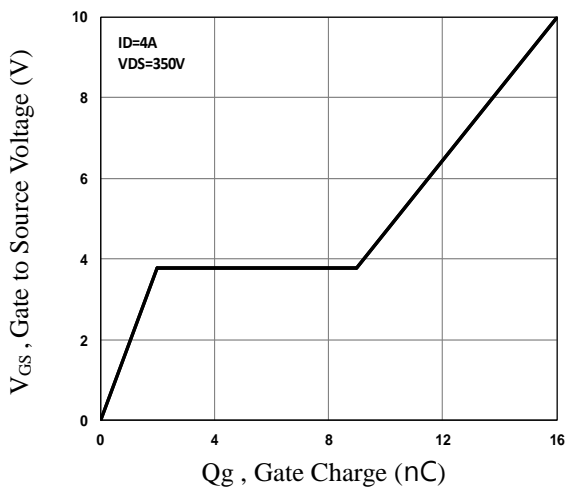
**Fig.2 Typical Output Characteristics**



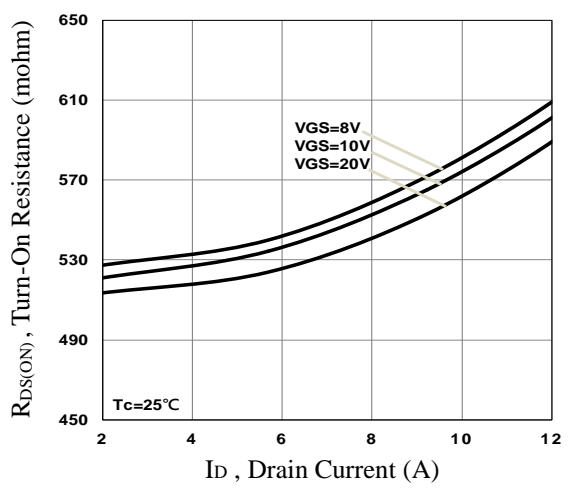
**Fig.3 Normalized R<sub>DS(on)</sub> vs. T<sub>J</sub>**



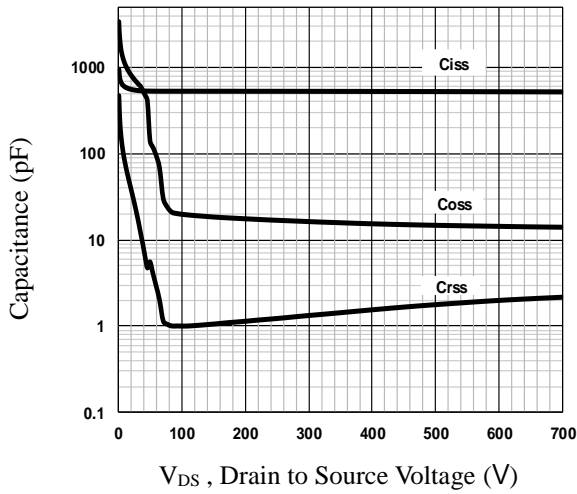
**Fig.4 Normalized V<sub>th</sub> vs. T<sub>J</sub>**



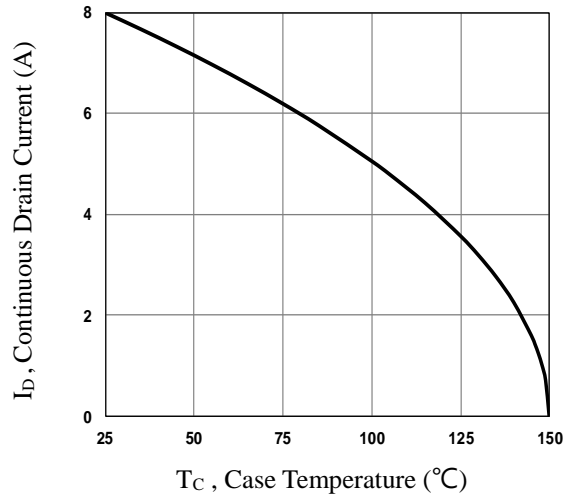
**Fig.5 Gate Charge Characteristics**



**Fig.6 Turn-On Resistance vs. I<sub>D</sub>**



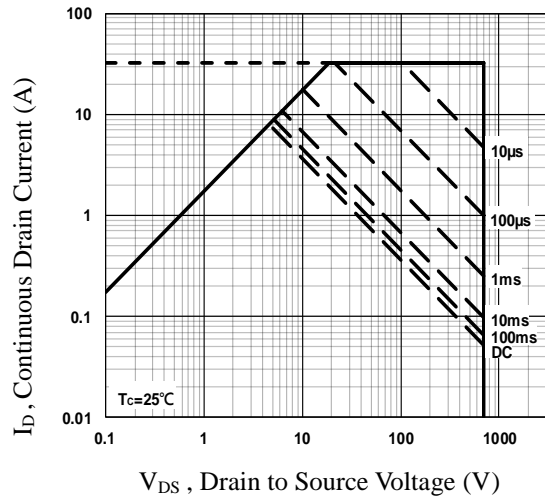
**Fig.7 Capacitance Characteristics**



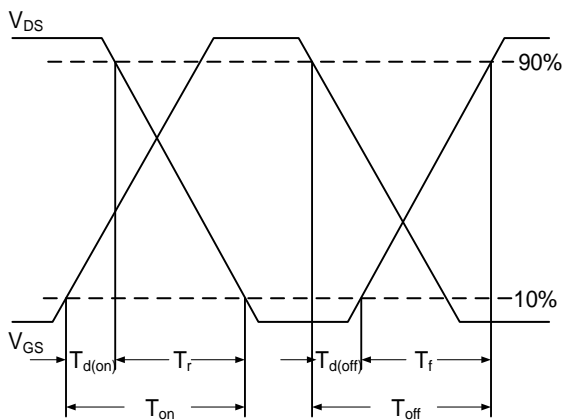
**Fig.8 Continuous Drain Current vs. Tc**



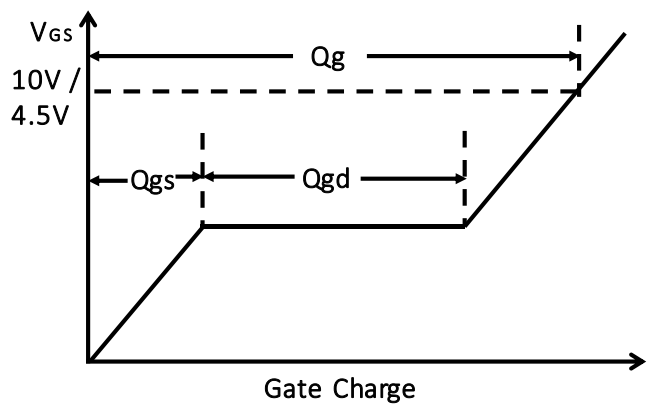
**Fig.9 Normalized Transient Impedance**



**Fig.10 Maximum Safe Operation Area**

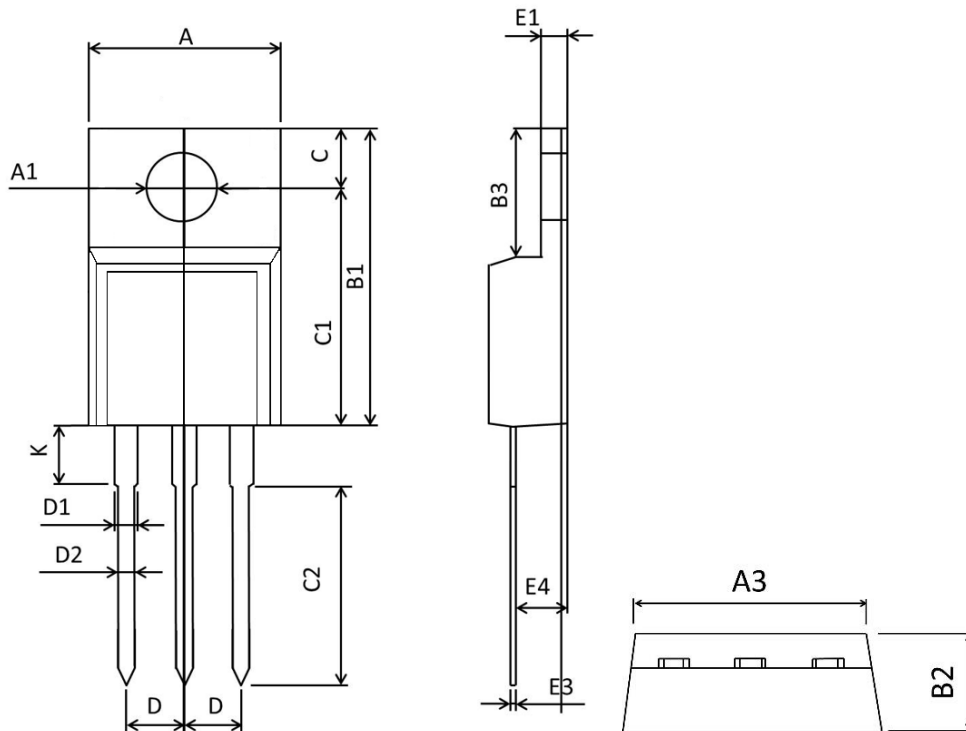


**Fig.11 Switching Time Waveform**



**Fig.12 Gate Charge Waveform**

## TO220F PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	9.860	10.460	0.389	0.411
A1	3.100	3.500	0.122	0.138
B1	15.450	16.300	0.608	0.642
B2	4.400	5.000	0.173	0.197
B3	6.280	7.100	0.247	0.280
C	3.100	3.500	0.122	0.138
C1	12.270	12.870	0.483	0.507
C2	9.600	10.520	0.378	0.414
D	2.540BSC		0.1BSC	
D1	1.070	1.470	0.042	0.058
D2	0.600	1.000	0.024	0.039
K	2.800	3.500	0.110	0.138
E1	2.340	2.740	0.092	0.108
E3	0.350	0.650	0.014	0.026
E4	2.460	2.960	0.097	0.117